

November 3, 2022

Dear Dayton Development Coalition Committee,

If the proposal submitted by Dean Gül E. Kremer, of the University of Dayton, entitled "The SW Ohio Integrated Microsystems Workforce & Research Center" to Dayton Development Coalition is selected for funding, it is Intel Corporation's intent to collaborate as detailed in the Project Description or the Facilities, Equipment and Other Resources section of the proposal.

If you have further questions, do not hesitate to contact me at gabriela.cruz.thompson@intel.com.

Sincerely,

Gabriela Cruz Thompson

Senior Director, Intel University Research and Collaboration



November 1, 2022

To:

Tony Ponder, Ed.D.

Provost

Sinclair Community College

From:

Paul Benson, Ph.D.

Provost and Executive Vice President of Academic Affairs

University of Dayton

Subject:

Statement of cooperation

SW Ohio Integrated Microsystems Workforce and Research Center

In light of the Intel Corporation's major investment in Ohio for semiconductor fabrication and related educational and research initiatives in microelectronics, the Dayton region and southwest Ohio have a compelling interest in contributing to the education and training of the workforce that Intel, along with many of its suppliers, will require. As our region already has significant educational and research capabilities in multiple areas of advanced manufacturing, and given the longstanding, fruitful partnership between the University of Dayton and Sinclair Community College, it would be valuable for our two institutions to look for meaningful opportunities to collaborate in meeting the workforce and research needs of the semiconductor industry.

The University of Dayton is submitting a project proposal this month to our region's Priority Development and Advocacy Committee to fund \$2.5M of the equipment that would be needed to establish a Class 100 cleanroom laboratory facility designed to provide the Dayton region the capacity to educate and train students for positions in the microelectronics and semiconductor engineering fields. Sinclair Community College is invited to be a primary partner in this initiative, building curriculum and experiential learning opportunities through the proposed microsystems center that will expand this region's workforce development pipeline for the semiconductor industry.

In agreeing to cooperate as a partner in the proposed center, Sinclair is not assuming any financial or administrative responsibility for the development or operation of the proposed microsystems center. This statement of cooperation expresses the shared intention between the University of Dayton and Sinclair to work collaboratively to activate the proposed center, should it be funded, for mutually agreed upon education and training goals and initiatives.

Panl A. Benson

11/2/22

Paul H. Benson, Ph.D. / Date For the University of Dayton

Anthony M. Ponder Ed D

11/3/2022

Anthon M. Ponder, Ed.D. /
For Sinclair Community College

November 3, 2022

The Dayton Region Priority Development & Advocacy Committee c/o Dayton Development Coalition 1401 South Main Street Dayton, OH 45402

Dear Dayton Region Priority Development and Advocacy Committee,

I am writing in enthusiastic support of the SW Ohio Integrated Microsystems Workforce & Research Center request from the University of Dayton. The University's School of Engineering has a long and successful history of developing microelectronic innovations. Some of these innovations have been licensed and adopted by major consumer electronics companies. With the entry of Intel and other semiconductor manufacturers to Ohio, there is a tremendous opportunity to translate UD innovations to the benefit of Ohio's economy.

The University has a core of world-class researchers and capabilities in the semiconductor and advanced manufacturing fields to build upon. The University's strategic plans to support the State's objectives in this area call for UD:

- To become a national leader in targeted areas of semiconductor engineering (e.g., Materials, Thin film Devices, Silicon Photonics, Photonics packaging, Systems Engineering, Waste remediation),
- Create a comprehensive multi-user facility that can be used as a vertically integrated training center for Design to Fabrication, Packaging and Testing that rivals other institutions, and
- Produce engineers, technologists and scientists skilled in semiconductor engineering/manufacturing.

The requested project is necessary to update and focus UD capabilities to be in alignment with emerging Ohio manufacturers. The requested project will also support workforce development in semiconductors and related areas which will be essential to Ohio capturing new industries and relocations or expansions of related industries. UD is teamed with Sinclair Community College in this endeavor, creating a continuous workforce development path from two-year degrees through graduate degrees.

The University is strongly committed to supporting future Ohio workforce needs and will execute this project to the fullest potential if awarded. Should you have any

questions, please do not hesitate to contact me at: <a href="john.leland@udri.udayton.edu">john.leland@udri.udayton.edu</a> or Dr. Gül Kremer at: <a href="gkremer1@udayton.edu">gkremer1@udayton.edu</a>

Sincerely,

John E. Leland, PhD. Vice President for Research University of Dayton

-Dheland